

FORM PTO-1449  
(REV.7-80)U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.  
34075/USAPPLICATION NO.  
10/783,163**INFORMATION DISCLOSURE STATEMENT**

(Use several sheets if necessary)

APPLICANT(S)  
Peter C. SalmonFILING DATE  
February 19, 2004GROUP ART UNIT  
2826**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	4,455,654	6/19/84	Bhaskar et al.	714	28	
	AB	4,748,495	5/31/88	Kucharek	257	713	
	AC	4,862,322	8/29/89	Bickford et al.	361	718	
	AD	5,001,548	3/19/91	Iversen	257	714	
	AE	5,070,297	12/3/91	Kwon et al.	324	754	
	AF	5,159,529	10/27/92	Lovgren	361	699	
	AG	5,162,974	11/10/92	Currie	361	702	
	AH	5,214,250	5/25/93	Cayson et al.	438	73	
	AI	5,239,200	8/24/93	Messina et al.	257	714	
	AJ	5,239,448	8/24/93	Perkins et al.	361	764	
	AK	5,267,867	12/7/93	Agahdel et al.	439	73	
	AL	5,281,151	1/25/94	Arima et al.	439	68	
	AM	5,290,970	3/1/94	Currie	174	250	
	AN	5,291,064	3/1/94	Kurokawa	257	714	
	AO	5,305,184	4/19/94	Andresen et al.	361	699	
	AP	5,367,593	11/22/94	Lebby et al.	385	53	
	AQ	5,461,327	10/24/95	Shibata et al.	324	760	
	AR	5,510,758	4/23/96	Fujita et al.	333	247	
	AS	5,579,574	12/3/96	Colleran et al.	29	840	
	AT	5,627,406	5/6/97	Pace	257	700	
	AU	5,635,767	6/3/97	Wenzel et al.	257	778	
	AV	5,640,051	6/17/97	Tomura et al.	257	778	
	AW	5,701,666	12/30/97	DeHaven et al.	29	831	
	AX	5,774,475	6/30/98	Qureshi	714	726	

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	AY	5,800,060	9/1/98	Speckbrock et al.	374	104	
	AZ	5,847,936	12/8/98	Forehand et al.	361	794	
	BA	5,900,738	05/04/99	Khandros et al.	324	761	
	BB	5,972,152	10/26/99	Lake et al.	156	247	
	BC	5,998,738	12/7/99	Li et al.	174	250	
	BD	6,103,554	8/14/00	Son et al.	438	126	
	BE	6,138,348	10/31/00	Kulesza et al.	29	840	
	BF	6,174,804	1/16/01	Hsu	438	238	
	BG	6,208,511	3/27/01	Bortolini et al.	361	698	
	BH	6,246,010	6/12/01	Zenner et al.	174	260	
	BI	6,304,447	10/16/01	Bortolini et al.	361	699	
	BJ	6,310,484	10/30/01	Akram et al.	324	764	
	BK	6,372,549	4/16/02	Urushima	438	118	
	BL	6,392,301	5/21/02	Waizman et al.	257	774	
	BM	6,392,301	2/4/03	Skinner et al.	361	800	
	BN	6,528,891	3/4/03	Lin et al.	257	778	
	BO	6,587,345	7/1/03	Chu et al.	361	719	
	BP	6,631,344	10/7/03	Kapur et al.	703	22	
	BQ	6,722,893	04/20/04	Li et al.	439	66	
	BR	6,763,880	7/20/04	Shih	165	80.4	
	BS	6,784,554	8/31/04	Kajiwara et al.	257	778	
	BT	6,845,477	1/18/05	Hidaka	714	729	
	BU	6,881,609	4/19/05	Salmon	438	107	
	BV	6,891,732	5/10/05	Takano et al.	361	783	

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	BW	6,927,471	8/9/05	Salmon	257	499	
	BX	6,938,678	9/6/05	Bortolini et al.	165	80.4	
	BY	6,942,493	9/13/05	Matsunaga et al.	439	66	
	CA	6,955,063	10/18/05	Adiga et al.	62	259.2	
	CB	6,956,284	10/18/05	Cady et al.	257	685	
	CC	6,956,285	10/18/05	Radu et al.	257	697	
	CD	6,973,717	12/13/05	Hacke et al.	29	840	
	CE	6,990,176	1/24/06	Sherman et al.	378	98.8	
	CF	7,009,412	3/7/06	Chong et al.	324	754	
	CG	7,040,383	5/9/06	Oyamada	165	104.33	
	CH	7,078,926	7/18/06	Khandros et al.	324	765	
	CI	7,163,830	1/16/07	Salmon et al.	438	18	
	CJ	7,254,024	8/7/07	Salmon	361	699	
	CK	US 2002/0121689	9/5/02	Honda	257	700	
	CL	US 2003/0106004	6/5/03	Richetti et al.	714	733	
	CM	US 2004/0148121	7/29/04	deObaldi et al.	702	117	
	CN	US 2004/0176924	9/9/04	Salmon	702	125	
	CO	US 2005/0040513	2/24/05	Salmon	257	734	
	CP	US 2005/0255722	11/7/05	Salmon	439	67	
	CQ	US 2006/0077638	04/13/06	Salmon	361	704	
	CR	US 2006/0131728	06/22/06	Salmon	257	698	
	CS	US 2006/0145715	7/6/06	Salmon	324	754	
	CT	US 2006/0209512	9/21/06	Taniguchi et al.	361	699	
	CU	US 2007/0007983	1/11/07	Salmon	324	754	

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	CV	US 2007/0023889	2/1/07	Salmon	257	690	
	CW	US 2007/0023904	2/1/07	Salmon	385	049	
	CX	US 2007/0023923	2/1/07	Salmon	257	296	
	CY	US 2007/0025079	2/1/07	Salmon	361	699	
	CZ						

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	DA	JP07169873A	7/4/95	Japan (English abstract)	H01L023	23		X
	DB							

**OTHER PRIOR ART** *(Including Author, Title, Date, Pertinent Pages, Etc.)*

	DC	Chow, Eugene M. et al., "Process Compatible Polysilicon-Based Electrical Through-Wafer Interconnects in Silicon Substrates," Journal of Microelectromechanical Systems, Vol. 11, No. 6, December 2002, pp 631-640
	DD	Davis & Arledge, "Thin Film Metallization of Three Dimensional Substrates," Electronic Components Technology Conference, Proceedings 44th, pp 359-361, May 1-4, 1994
	DE	Gutmann, R.J. et al., "Wafer-Level Three-Dimensional Ics: A Better Solution Than SoCs and SiPs?," 6 pages

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